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## Resonac Filed Patent Infringement Lawsuit on Photosensitive Films for Semiconductor Package Substrates and High-density Electronic Circuit Boards

In December 2023, Resonac Corporation (President: Hidehito Takahashi, hereinafter “Resonac”) and Resonac Materials (Dongguan) Co., Ltd. (President: Hiroshi Usami) cooperatively instituted a lawsuit at Shenzhen Intermediate People’s Court against four Chinese companies which manufacture and/or sell photosensitive films, alleging that these four Chinese companies are infringing Resonac’s patent in China on photosensitive films. In this lawsuit, Resonac and Resonac Materials (Dongguan) Co., Ltd. are co-plaintiffs, and Hunan Initial New Materials Co., Ltd., Hunan Hori New Materials Co., Ltd., Shenzhen Sanxi Electronic Circuit Co., Ltd. and Shenzhen Taiwei Precision Circuit Co., Ltd. are co-defendants.

Resonac instituted this lawsuit in order to claim injunction of the sale of photosensitive films which are currently manufactured and/or sold by the four companies in China, and compensation for damages from the sale of those photosensitive films, resting on the basis of Resonac’s patent in China on photosensitive films used for wiring on semiconductor package substrates and/or high-density electronic circuit boards.

Resonac will continue actively utilizing its intellectual properties in accordance with its business strategy and legally protecting intellectual properties, thereby promoting fair competition in the market and increasing the value of its technologies.

### [About the Resonac Group]

The Resonac Group is a new company established as a result of the integration of the Showa Denko Group and the Showa Denko Materials Group (former Hitachi Chemical Group) in January 2023. The Group’s annual sales of semiconductor and electronic materials amount to about 400 billion yen, accounting for about 30% of the Group’s annual net sales. The Group especially has an extensive lineup of semiconductor materials for packaging process which are adopted by many semiconductor-related manufacturers. The integration of the two companies has enabled the Resonac Group to design functions of materials as well as to develop them in-house, going all the way back to raw materials. The new trade name “RESONAC” was created as a combination of two English words, namely, the word of “RESONATE” and “C” as the first letter of CHEMISTRY. The Resonac Group will make the most of its co-creative platform, and accelerate technological innovation with semiconductor manufacturers, material manufacturers, and equipment manufacturers inside and outside Japan.

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